

Material Declaration Data Sheet

Model: Intel® Server Board S2600GZ/GL, Intel® Server System R1000GZ/GL product family, Intel® Server System R2000GZ/GL product family Manufacturer: Intel Corporation

Note: This declaration applies to all associated product codes starting on Page 2

Lead Free (Pb) Product: Yes/RoHS6, 6/6

Date: November 20, 2012

Restriction on Hazardous Substances (RoHS) Compliance

RoHS Definition

- Quantity limit of 0.1% by mass (1000PPM) for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE)
- Quantity limit of 0.01% by mass (100 PPM) for: Cadmium

Intel understands RoHS requires: Lead and other materials banned in the RoHS Directive are either (1) below all applicable substance thresholds as proposed by the EU or (2) an approved/pending exemption applies. (Note: RoHS implementing details are not fully defined and may change.)

RoHS Declaration

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- 6a Lead as an alloying element in steel containing up to 0.35 % lead by weight.
- **6b** Lead as an alloying element in aluminum containing up to 0.4 % lead by weight.
- 6c Lead as an alloying element in copper containing up to 4 % lead by weight.
- 7a Lead in high melting temperature type solders (i.e. lead based alloys containing 85 % by weight or more lead)
- **7b** Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications.
- 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.
- **7c-II** Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher.
- **7c-III** Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC.
- **8b** Cadmium and its compounds in electrical contacts.
- **11b** Lead used in other than C-press compliant pin connector systems.
- **13b** Cadmium and lead in filter glasses and glasses used for reflectance standards.
- 15 Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.
- 20 Lead oxide in glass used for bonding front and rear substrates of flat fluorescent lamps used for Liquid Crystal Displays (LCDs)
- 21 Lead and cadmium in printing inks for the application of enamels on glasses, such as borosilicate and soda lime glasses.
 - 24 Lead in solders for the soldering to machined through hole discoidal and planar array ceramic capacitors
 - 25 Lead oxide in surface conduction electron emitter displays (SED) used in structural elements: notably in the seal frit and frit ring.
 - 31 Lead in soldering materials in mercury free flat fluorescent lamps (which e.g. are used for liquid crystal displays, design or industrial lighting).
 - 33 Lead in solders for the soldering of thin copper wires of 100um diameter and less in power transformers.
 - 34 Lead in cermet-based trimmer potentiometer elements.
 - Other (Include exemption number)

Where the product is declared to meet RoHS requirements, it has been verified to be in conformance with 2011/65/EU as we currently understand the requirements. Intel has systems in place to verify conformance with all applicable environmental requirements and to the best of our knowledge the information is true and correct.

INTEL ACCEPTS NO DUTY TO UPDATE THIS DECLARATION OR TO NOTIFY USERS OF THIS DECLARATION OF UPDATES OR CHANGES TO THIS DECLARATION. INTEL SHALL NOT BE LIABLE FOR ANY DAMAGES, DIRECT OR INDIRECT, CONSEQUENTIAL OR OTHERWISE, SUFFERED BY USERS OR THIRD PARTIES AS A RESULT OF THE USERS RELIANCE ON INFORMATION IN THIS DECLARATION THAT HAS BEEN UPDATED OR CHANGED.

Product Code Information



Product Code	Description	*RoHS Exemption #		
R1304GZ4GS9	Integrated Server 1U System with basic configuration, 24 DIMMs	6a,6b,6c,7a,7c1,15		
R1304GL4DS9	Integrated server system with 4 SATA ports standard, 16 DIMMs	6a,6b,6c,7a,7c1,15		
	Integrated Server System with basic configuration, 24 DIMMs	6a,6b,6c,7a,7c1,15		
R1208GZ4GS9				
R2208GZ4GS9	Integrated Server System with basic configuration, 24 DIMMs	6a,6b,6c,7a,7c1,15		
R2208GL4DS9	Integrated Server System with 4 SATA ports and 16DIMM motherboard	6a,6b,6c,7a,7c1,15		
R2308GZ4GS9	Integrated Server System with basic configuration, 24 DIMMs	6a,6b,6c,7a,7c1,15		
R2308GL4DS9	Integrated Server System with 4 SATA ports standard, 16 DIMMs	6a,6b,6c,7a,7c1,15		
R2312GZ4GS9	Integrated Server System with basic configuration, 24 DIMMs	6a,6b,6c,7a,7c1,15		
R2224GZ4GC4	Integrated Server System with no extras	6a,6b,6c,7a,7c1,15		
A2UBKTMFBUSSD	Auxilary bracket for MFBU Mounting.	Compliant without exemption		
AXXDCCRPSCBL	Spare DC power cable	Compliant without exemption		
FXXFPANEL	Front Panel board spare for use on 1U/2U rack systems (R1000, R2000 except R2224 and R2312) Rack chassis and P4300 Pedestal Chassis	7c1		
BXSTS200PNRW	Spare narrow copper heatsink, for S2600GZ (24- DIMM) board	Compliant without exemption		
AXXELVRAIL	Enhanced Value Rail Kit	Compliant without exemption		
AXXPRAIL755	Short 1U/2U Premium Rail Kit, no CMA support	Compliant without exemption		
AXXRJ45DB93	Kit of RJ45 and Serial 10p to DB9 Cable Adapters	Compliant without exemption		
RES2SV240	24 Port SAS 6Gb expander card with ports configurable for input or output. Retail SKU includes cables.	7a, 7c1, 15		
AXXCBL500MSMS	Kit of 2 cables, 500mm length, straight SFF-8087 to SFF- 8087 connectors.	Compliant without exemptions		
AXXCBL650MSMS	Kit of 2 cables, 650mm length, straight SFF-8087 to SFF- 8087 connectors.			
AXXCBL730MSMS	Kit of 2 cables, 730mm length, straight SFF-8087 to SFF- 8087 connectors. Spare for R2308	Compliant without exemptions		
AXXCBL600MSMS	8087 connectors.	Compliant without exemptions		
AXXCBL585MSMR	Kit of 2 cables, 585mm length, straight SFF-8087 to right angle SFF-8087 connectors.			
AXXCBL850MS7R	Kit of 2 cables, 850mm length, straight SFF-8087 to right angle 7-pin SATA connectors.			
AXXCBL730MRMR	Kit of 2 cables, 730mm length, right angle SFF-8087 to right angle SFF-8087 connectors.			
AXXCBL550MRMR	Kit of 2 cables, 550mm length, right angle SFF-8087 to right angle SFF-8087 connectors.			
AXXCBL1030MR7R	Kit of 2 cables, 1030mm length, right-angle SFF-8087 to	Compliant without exemptions		

	right angle 7-pin SATA connectors.				
AXXCBL770MSMR	Kit of 2 cables, 770mm length, straight SFF-8087 to right angle SFF-8087 connectors.	Compliant without exemptions			
AXXCBL165MSMS	Kit of 2 cables, 165mm length, straight SFF-8087 to right angle SFF-8087 connectors. Works for: : integrated expander RES2CV240 and RES2CV240 connection, chassis R2200 family.	Compliant without exemptions			
AXXCBL185MSMS	Kit of 2 cables,185mm length, straight SFF-8087 to right angle SFF-8087 connectors. Works for: : integrated expander RES2CV240 and RES2CV240 connection, chassis R2200 family.	Compliant without exemptions			
AXXCBL245MSMS	Kit of 2 cables, 245mm length, straight SFF-8087 to right angle SFF-8087 connectors. Works for: : integrated expander RES2CV240 and RES2CV240 connection, chassis R2200 family.	Compliant without exemptions			
AXXCBL880SATA	SATA Cable Accessory	Compliant without exemptions			
AXXRPFKSSD2	Upgrade Key to enable SSD Cache with Fastpath I/O for Intel's RAID RS25 family of ROC products.	7c1			
AXXRPFKDE2	Upgrade Key to enable Drive Encryption Management for Intel's RAID RS25 family of ROC products	7c1			
AXXRPFKSNSH2	Upgrade Key to enable Rapid Recovery Snapshot for Intel's RAID RS25 family of ROC products.	7c1			
R1304GZ4GC	S2600GZ4 board in 1U chassis, ODD bay for CD/DVD drive support , 4x3.5" HS HDD	6a,6b,6c,7a,7c1,15			
R2312GZ4GC4	S2600GZ4 board in 2U chassis, no ODD, 2 SSD mount locations on air duct, 12x3.5/2.5" HS HDD Support, 12 ports, two 750W PSUs	6a,6b,6c,7a,7c1,15			
R1208GZ4GC	S2600GZ4 board (S2600GZ4) in 1U chassis, ODD bay for CD/DVD drive support , 8x2.5" HS HDD support	6a,6b,6c,7a,7c1,15			
R1208GZ4GCSAS	Integrated Server System with 8 HW SAS ports standard, 24 DIMMs	6a,6b,6c,7a,7c1,15			
R1208GZ4GCIOC	Integrated Server System with 8 Entry-Raid SAS ports standard, 24 DIMMs	6a,6b,6c,7a,7c1,15			
R1208GL4DS	Integrated Server System with 16 DIMM board and 8 SATA ports, 16 DIMMs	6a,6b,6c,7a,7c1,15			
R2208GL4GS	Integrated Server System with 8 SATA 2.5" drives and 16DIMM motherboard, 16 DIMMs	6a,6b,6c,7a,7c1,15			
R2208GZ4GC	Integrated Server System with 8 SATA ports standard, 24 DIMMs	6a,6b,6c,7a,7c1,15			
R2208GZ4GCSAS	Integrated Intel Server System with 8 HW RAID SAS ports standard, 24 DIMMs	6a,6b,6c,7a,7c1,15			
R2208GZ4GC10G	Integrated Server System with pre-installed dual port SFP+ 10GB IOM, 24 DIMMs	6a,6b,6c,7a,7c1,15			
R2208GZ4IS	Integrated Server System with 48V DC power supply, 24 DIMMs	6a,6b,6c,7a,7c1,15			
R2312GL4GS	Integrated Server System with 16 DIMM board and open storage configuration, 16 DIMMs	6a,6b,6c,7a,7c1,15			
R2216GZ4GCLX	Integrated Server System with pre-installed 10G, 8 SAS HW Raid module and expander, 24 DIMMs	6a,6b,6c,7a,7c1,15			
R2308GZ4GC	Integrated Server System with 8 SATA ports standard, 24 DIMMs	6a,6b,6c,7a,7c1,15			
R2308GL4GS	Integrated Server System with 8 SATA ports standard, 16 DIMMs	6a,6b,6c,7a,7c1,15			
R2308GZ4GCIOC	Integrated Server System with 8 Entry-RAID SAS ports standard, 24 DIMMs	6a,6b,6c,7a,7c1,15			
R2216GZ4GC	Integrated Intel Server System with 16 SAS ports standard, 6a,6b,6c,7a,7c1,15 24 DIMMs				
R2216GZ4GCIOC	Integrated Intel Server System with 16 SAS ports standard,	6a,6b,6c,7a,7c1,15			

	24 DIMMs		
R2312GZ4GCSAS	Integrated Intel Server System with 12 SAS ports standard, 24 DIMMs	6a,6b,6c,7a,7c1,15	
R2224GZ4GCSAS	Integrated Intel Server System	6a,6b,6c,7a,7c1,15	
S2600GZ4	Intel Server Board S2600GZ4 Supports dual Intel Xeon E5- 2600 processors	7a, 7c1, 15	
S2600GL4	Intel Server Board S2600GL4 Supports dual Intel Xeon E5- 2600 processors; 16 DIMMs	7a, 7c1, 15	
A2USTOPANEL	Storage rack ear control panel kit	Compliant without exemption	
A2U8X25HSDK	Spare/accessory 8x2.5" HDD drive upgrade kit for 2Usystem.	Compliant without exemption	
A2U8X25DPDK	Spare/accessory Dual Ported 8x2.5" HDD drive upgrade kit for 2Usystem.	Compliant without exemption	
AXXQAAIOMOD	Intel Quick Assist Accelerator I/O Module Mezz Card	7c1	
AXXQAAPCIE	Intel Quick Assist Accelerator PCIe card	7c1	
F1UL16RISER	Riser Spare, 1U, PCIex16FHHL	7c1	
A2UL8RISER	Spare 2U 3 slot riser for GZ/GL/BB boards	7c1	
A2UL16RISER	Accessory 2U 2 slot riser for GZ/GL/BB boards:	7c1	
A2ULPCIXRISER	2U PCI-X riser for GZ/GL/BB boards	7c1	
FR1000FAN10P	Two spare fan for 1U R1000GZ/GL/BB System	7a, 7c1	
FR2000FAN60HS	Two spare fan for 2U R2000GZ/GL/BB System	7a, 7c1	
AXXVRAIL	Value Rail Kit	Compliant without exemption	
AXXPRAIL	1U/2U Premium Rail Kit	Compliant without exemption	
AXX1U2UCMA	Cable management arm for Premium 1U/2U rail kit	Compliant without exemption	
AXX2POSTBRCKT	Fixed mount bracket kit for 2-post racks	Compliant without exemption	
AXXSATADVDROM	Slimline SATA DVDROM Device	6c, 7c1	
AXXSATADVDRWROM	Slim SATA DVD+/-RW ROM Accessory	6c, 7c1	
A1UBEZEL	1U locking bezel	Compliant without exemption	
A2UBEZEL	2U locking bezel	Compliant without exemption	
FFPANEL	Front Panel board spare for P4000 server chassis	7c1, 7c2	
A1U2ULCP	LCP Module (local control panel)	7c1	
FPWRCABLENA	North American Power Cord Spare	Compliant without exemption	
FR1304HSBP	Hot swap backplane board spare for 1U 4x3.5" chassis	7c1	
FXXEA91X91HS	91.5x91.5 Heatsink for S2600GL (16 DIMM) board	Compliant without exemption	
FXX8X25HSBP	8x2.5" hot swap HSBP spare (for R2200, and P4200 Chassis families)	7c1	
FXX8X25DPBP	Spare 8x2.5" Dual Port Hot Swap Backplane	7c1	
F2U8X35HSBP	Hot swap backplane board spare for 2U 8x3.5" chassis	7c1	
F1U8X25HSBP	Hot swap backplane board spare for 1U 8x2.5" chassis	7c1	
F2U12X35HSBP	Hot swap backplane board spare for 2U 12x3.5" chassis	7c1	
FXX35HSADPB	3.5" HDD Hot Swap Drive Carrier spares for P4300 chassis	Compliant without exemption	
FXX25HSCAR	2.5" HDD Hot Swap Drive Carrier spares for P4200	Compliant without exemption	
RMS25PB080	Intel® Integrated RAID Module RMS25PB080, PCIe Slot, LSI2208 ROC, 8P Internal SAS/SATA	7a, 7c1, 15	
RMS25PB040	Intel® Integrated RAID Module RMS25PB040, PCIe Slot, LSI2208 ROC, 4P Internal SAS/SATA	7a, 7c1, 15	
RMT3PB080	Intel® Integrated RAID Module RMT3PB080, PCIe Slot, LSI2208 ROC, 8P Internal SATA (only)	7a, 7c1, 15	

RMS25KB080	Intel® Integrated RAID Module RMS25KB080, PCIe Slot, LSI2308 I/O Controller, 8P Internal SAS	7a, 7c1, 15
RMS25KB040	Intel® Integrated RAID Module RMS25KB040, PCIe Slot, LSI2308 SAS Chip, 4P Internal SAS, LSI IR RAID 0,1,1E	7a, 7c1, 15
RMS25CB080	Intel® Integrated RAID Module RMS25CB080, SIOM Connector, LSI2208 ROC, 8P Internal SAS, MegaRAID SWStack, 1GB DDR3, R0,1,10,5,50,6,60	7a, 7c1, 15
RMS25CB040	Intel® Integrated RAID Module RMS25CB040, SIOM Connector, LSI2208 ROC, 4P Internal SAS, MegaRAID SWStack, 1GB DDR3, R0,1,10,5,50,6,60	7a, 7c1, 15
RMT3CB080	Intel® Integrated RAID Module RMT3CB080, SIOM Connector, LSI2208 ROC, 8P Internal SATA (only), MegaRAID SWStack, 512MB DDR3, R0,1,10,5,50,6,60	7a, 7c1, 15
RMS25JB080	Intel® Integrated RAID Module RMS25JB080, SIOM Module Slot, LSI2308 SAS Chip, 8P Internal SAS, LSI IR RAID 0,1,1E	7a, 7c1, 15
RMS25JB040	Intel® Integrated RAID Module RMS25JB040, SIOM Module Slot, LSI2308 SAS Chip, 4P Internal SAS, LSI IR RAID 0,1,1E	7a, 7c1, 15
AXX1FDRIBIOM	Single port, FDR speed Infiniband module with QSFP	7a, 7c1, 15
AXX2FDRIBIOM	Dual port, FDR speed Infiniband module with QSFP	7a, 7c1, 15
AXXTPME5	Trusted Platform Module for server systems	7c1
RES2CV240	Integrated 24-port 6G SAS expander	7a, 7c1, 15
RES2CV360	Integrated 36-port 6G SAS expander	7a, 7c1, 15
AXX4P1GBPWLIOM	Quad port 1GbE IO Module ,Intel® Ethernet Controller I350	7a, 7c1, 15
AXX10GBTWLIOM	Dual RJ-45 port 10GBASE-T IO module, Intel I350 Ethernet	7a, 7c1, 15
AXX10GBNIAIOM	Dual SFP+ port 10GbE IO module,Intel® 82599 10 Gigabit	7a, 7c1, 15
AXXRSBBU9	Intel® RAID Smart Battery AXXRSBBU9 for mainstream RS25, RMS25, RT3 and RMT3 family RAID products.	6a, 7c1
AXXRMFBU2	Maintenance-Free Backup Unit, NAND Flash, Supercapacitor	6a, 7c1
RKSATA4R5	Intel® RAID C600 Upgrade Key RKSATA4R5, Black	7c1
RKSATA8	Activation key for 8 SATA ports and includes RSTe SW RAID 0/1/10/5 and LSI SW RAID 0/1/10 , Blue	7c1
RKSATA8R5	Activation key for 8 SATA ports and includes RSTe SW RAID 0/1/10/5 & LSI SW RAID 0/1/10/5 (LSI SWR5), White	7c1
RKSAS4	Intel® RAID C600 Upgrade Key RKSAS4, Green	7c1
RKSAS4R5	Intel® RAID C600 Upgrade Key RKSAS4R5, Yellow	7c1
RKSAS8	Activation key for 8 SAS ports and includes RSTe SW RAID 0/1/10 (no RAID 5) & LSI SW RAID 0/1/10 , Orange	7c1
RKSAS8R5	Activation key for 8 SAS ports and includes RSTe SW RAID 0/1/10 (no RAID5) & SW RAID 0/1/10/5 (LSI SWR5), Purple	7c1
AXXRMM4R	Remote Management Module, KVM ,Dedicated NIC module	7c1
AXXRMM4LITE	Remote Management Module for upgrading to Remote KVM	7c1
FXX460GCRPS	460W Common Redundant PS, 80 Plus Gold Efficiency	6a,6b,6c,7a,7c1
FXX750PCRPS	750W Common Redundant PS, 80 Plus Platinum Efficiency	6a,6b,6c,7a,7c1
FXX750DCCRPS	750W Direct Current CRPS 80+ Gold Efficiency	6a,6b,6c,7a,7c1

* RoHS Exemption # corresponds with exemption #'s found on page 1.

关于符合中国《电子信息产品污染控制管理办法》的声明

Management Methods on Control of Pollution from Electronic Information Products (China RoHS declaration)

产品中有毒有害物质的名称及含量

部件名称	有毒有害物质或元素						
(Parts)	铅	汞	镉	六价铬	多溴联苯	多溴二苯醚	
	(Pb)	(Hg)	(Cd)	(Cr6+)	(PBB)	(PBDE)	
主板组件	X	0	0	0	0	0	
Motherboard Assembly	~	0	0	0	0	U	
O: 表示该有毒有害物质在该部件	†所有均	质材料□	中的含量	均在 SJ/T	11363-2006	标准规定的	
限量要求以下。							
O: Indicates that this hazar	dous su	bstance	contai	ned in al	1 homogeneo	ous	
materials of this part is bel	ow the	limit r	equirem	ent in SJ	/T 11363-20	006.	
×:表示该有毒有害物质至少在该部件的某一均质材料中的含量超出 SJ/T 11363-2006 标准							
规定的限量要求。							
imes: Indicates that this hazardous substance contained in at least one of the							
homogeneous materials of this part is above the limit requirement in SJ/T 11363- $$							
2006.							
对销售之日的所售产品,本表显示我公司供应链的电子信息产品可能包含这些物质。注意:							
在所售产品中可能会也可能不会含有所有所列的部件.							
This table shows where these substances may be found in the supply chain of our							
electronic information products, as of the date of sale of the enclosed product.							
Note that some of the component types listed above may or may not be a part of							
the enclosed product.							
除非另外特别的标注,此标志为针对所涉及产品的环保使用期限标志.某些可更换的零							
部件可能会有一个不同的环保使用期限(例如,电池单元模块).							

此环保使用期限只适用于产品在产品手册中所规定的条件下工作.



The Environment-Friendly Use Period (EFUP) for all enclosed products and their parts are per the symbol shown here, unless otherwise marked. Certain fieldreplaceable parts may have a different EFUP (for example, battery modules) number. The Environment-Friendly Use Period is valid only when the product is operated under the conditions defined in the product manual.

关于符合中国《电子信息产品污染控制管理办法》的声明 Management Methods on Control of Pollution from Electronic Information Products (China RoHS declaration)

产品中有毒有害物质的名称及含量

部件名称	有毒有害物质或元素 (Hazardous Substance)					
(Parts)	铅	汞	镉	六价铬	多溴联苯	多溴二苯醚
	(Pb)	(Hg)	(Cd)	(Cr6+)	(PBB)	(PBDE)
机箱子组件	×	0	\cap	\cap	\bigcirc	\bigcirc
Chassis subassembly		0)	0)	0
电源	×	0	\cap	\cap	\cap	\bigcirc
Power Supply	~	\bigcirc		\bigcirc		\bigcirc
印刷板组件						
Printed Board Assemblies	×	0	0	0	0	0
(PBA)						

O: 表示该有毒有害物质在该部件所有均质材料中的含量均在 SJ/T 11363-2006 标准规定的 限量要求以下。

O: Indicates that this hazardous substance contained in all homogeneous materials of this part is below the limit requirement in SJ/T 11363-2006. X: 表示该有毒有害物质至少在该部件的某一均质材料中的含量超出 SJ/T 11363-2006 标准 规定的限量要求。

 $\times:$ Indicates that this hazardous substance contained in at least one of the homogeneous materials of this part is above the limit requirement in SJ/T 11363-2006.

对销售之日的所售产品,本表显示我公司供应链的电子信息产品可能包含这些物质。注 意:在所售产品中可能会也可能不会含有所有所列的部件

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关于符合中国《电子信息产品污染控制管理办法》的声明 Management Methods on Control of Pollution from Electronic Information Products (China RoHS declaration)

产品中有毒有害物质的名称及含量

部件名称	有毒有害物质或元素							
(Parts)	铅	汞	福	六价铬	多溴联苯	多溴二苯醚		
	(Pb)	(Hg)	(Cd)	(Cr6+)	(PBB)	(PBDE)		
印刷板组件								
Printed Board Assemblies	\times	0	0	0	0	0		
(PBA)								
O: 表示该有毒有害物质在该部件	O: 表示该有毒有害物质在该部件所有均质材料中的含量均在 SJ/T 11363-2006 标准规定的							
限量要求以下。								
O: Indicates that this hazardous substance contained in all homogeneous								
materials of this part is bel	ow the	limit r	equirem	ent in SJ	/T 11363-20	006.		
×:表示该有毒有害物质至少在该部件的某一均质材料中的含量超出 SJ/T 11363-2006 标准								
规定的限量要求。								
$ imes_{:}$ Indicates that this hazardous substance contained in at least one of the								
homogeneous materials of this	part i	s above	the li	mit requi	rement in S	SJ/T 11363-		
2006.								
对销售之日的所售产品,本表显示我公司供应链的电子信息产品可能包含这些物质。注意:								
在所售产品中可能会也可能不会含有所有所列的部件								
This table shows where these substances may be found in the supply chain of our								
electronic information products, as of the date of sale of the enclosed product.								
Note that some of the component types listed above may or may not be a part of								
the enclosed product.								
除非另外特别的标注,此标志为针对所涉及产品的环保使用期限标志.某些可更换的零								
部件可能会有一个不同的环保使用期限(例如,电池单元模块).								

此环保使用期限只适用于产品在产品手册中所规定的条件下工作.



The Environment-Friendly Use Period (EFUP) for all enclosed products and their parts are per the symbol shown here, unless otherwise marked. Certain fieldreplaceable parts may have a different EFUP (for example, battery modules) number. The Environment-Friendly Use Period is valid only when the product is operated under the conditions defined in the product manual.